L Number	Hits	Search Text	DB	Time stamp
1	922	438/687.ccls.	USPAT	2004/09/23
				13:04
2	710	438/694.ccls.	USPAT	2004/09/23
				13:07
3	1597	438/692.ccls.	USPAT	2004/09/23
		·		13:08
4	606	438/669.ccls.	USPAT	2004/09/23
				13:08
5	250	438/658.ccls.	USPAT	2004/09/23
				13:09
6	260	438/659.ccls.	USPAT	2004/09/23
				13:10
7	197	438/645.ccls.	USPAT	2004/09/23
·		,	JOIAI	13:10
8	122	438/707.ccls.	USPAT	2004/09/23
~	122		JOFAI	13:11
9	758	438/710.ccls.	HEDAT	1
9	196	+JO// IV.CCIS.	USPAT	2004/09/23
40	^F^	429/720	HODET	13:11
10	658	438/720.ccls.	USPAT	2004/09/23
				13:14
11	31	west-jeffrey\$.in. barth-michael\$.in.	USPAT	2004/09/23
		zuhoski-steven\$.in.		13:14
12	11	west-jeffrey\$.in. barth-michael\$.in.	US-PGPUB	2004/09/23
		zuhoski-steven\$.in.		13:14
13	26	west-jeffrey\$.in. barth-michael\$.in.	EPO; JPO;	2004/09/23
		zuhoski-steven\$.in.	DERWENT;	13:14
			IBM_TDB	
14	8497	(copper "cu") same (polish\$6 cmp)	USPAT	2004/09/23
				13:25
15	5430	((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)		13:24
16	3587	(((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)) and ((silane silicon) same		13:16
		(copper "cu"))		
17	1968	((((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)) and ((silane silicon) same		13:25
		(copper "cu"))) and plasma		,
18	567	(((((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
	,	(silane silicon)) and ((silane silicon) same		13:24
		(copper "cu"))) and plasma) and (((copper		
		"cu") adj2 (polish\$6 cmp)) ((polish\$6 cmp)		
İ		adj2 (copper "cu")))		
19	1326	(((copper "cu") adj2 (polish\$6 cmp))	US-PGPUB	2004/09/23
		((copper cu) adj2 (polisiist cliip)) ((polish\$6 cmp) adj2 (copper "cu")))	- CO-1 GF 0B	13:24
20	1086	((((copper "cu") adj2 (polish\$6 cmp))	IIS DODIE	2004/09/23
4 U	1000		US-PGPUB	1
.		((polish\$6 cmp) adj2 (copper "cu")))) and		13:26
_		(silane silicon)		000 6/00/55
22	533	(((((copper "cu") adj2 (polish\$6 cmp))	US-PGPUB	2004/09/23
	·	((polish\$6 cmp) adj2 (copper "cu")))) and		13:25
		(silane silicon)) and plasma		

23	4434	(copper "cu") same (polish\$6 cmp)	EPO; JPO;	2004/09/23
			DERWENT;	13:25
		,	IBM_TDB	
24	483	((copper "cu") same (polish\$6 cmp)) and	EPO; JPO;	2004/09/23
		(silane silicon)	DERWENT;	13:26
			IBM_TDB	